



Material Content Data Sheet



Sales Product Name		BSP742T		Issued		25. January 2018		
MA#		MA001173648						
Package		PG-DSO-8-24		Weight*		83.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.250	1.50	1.50	15045	15045
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.717	0.86		8634	
wire	non noble metal	copper	7440-50-8	29.121	35.06	35.97	350564	359738
	noble metal	gold	7440-57-5	0.373	0.45	0.45	4491	4491
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1193
plastics	plastics	epoxy resin	-	4.560	5.49		54898	
	inorganic material	silicondioxide	60676-86-0	44.910	54.07	59.68	540628	596719
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9797	9797
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7828	7828
glue	plastics	epoxy resin	-	0.093	0.11		1117	
	noble metal	silver	7440-22-4	0.437	0.53	0.64	5265	6382
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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